

IN THE CLAIMS:

Please CANCEL claims 40, 46, 47, 50 and 51 without prejudice to or disclaimer of the recited subject matter.

For the Examiner's convenience, all claims currently pending in this application have been reproduced below:

1-19. (Cancelled)

20. (Previously Presented) An exposure apparatus comprising:

an optical system, which directs an exposure beam emitted from a light source onto a substrate, said optical system including a casing and an optical element, said casing having a closed space and said optical element being disposed in the closed space;

a first supplier, which supplies an inert gas into the closed space;

a second supplier, which supplies a gas, containing oxygen, into the closed space;

a discharger, which discharges the gas from the closed space; and

a controller for changing a wavelength of the exposure beam between an exposure process for the substrate and a cleaning process for the optical element,

wherein said controller controls said first supplier and said second supplier.

21. (Previously Presented) An apparatus according to Claim 20, wherein said first supplier comprises a first valve, said second supplier comprises a second valve and said controller controls said first valve and said second valve.

22. (Previously Presented) An apparatus according to Claim 20, wherein said controller controls a concentration of oxygen in the closed space.

23-25. (Cancelled)

26. (Previously Presented) An exposure apparatus comprising:

an optical system, which directs an exposure beam emitted from a light source onto a substrate, said optical system including a casing and an optical element, said casing having a closed space and said optical element being disposed in the closed space;

a first supplier, which supplies an inert gas into the closed space;

a second supplier, which supplies a gas, containing oxygen, into the closed space;

a discharger, which discharges the gas from the closed space; and

a controller for changing a wavelength of the exposure beam between an exposure process for the substrate and a cleaning process for the optical element,

wherein said controller changes the wavelength of the exposure beam into a wavelength region higher than an oxygen absorptivity when said second supplier supplies the oxygen.

27. (Previously Presented) An exposure apparatus comprising:

an optical system, which directs an exposure beam emitted from a light source onto a substrate, said optical system including a casing and an optical element, said casing having a closed space and said optical element being disposed in the closed space;

a first supplier, which supplies an inert gas into the closed space;

a second supplier, which supplies a gas, containing oxygen, into the closed space;

a discharger, which discharges the gas from the closed space; and

a controller for changing a wavelength of the exposure beam between an exposure process for the substrate and a cleaning process for the optical element,

wherein said controller changes the wavelength of the exposure beam to a shorter wavelength when said second supplier supplies the oxygen.

28. (Previously Presented) An exposure apparatus comprising:

an optical system, which directs an exposure beam emitted from a light source onto a substrate, said optical system including a casing and an optical element, said casing having a closed space and said optical element being disposed in the closed space;

a first supplier, which supplies an inert gas into the closed space;

a second supplier, which supplies a gas, containing oxygen, into the closed space;

a discharger, which discharges the gas from the closed space;

a controller for changing a wavelength of the exposure beam between an exposure process for the substrate and a cleaning process for the optical element; and  
a laser control device which changes the emission laser wavelength region, wherein said controller controls said laser control device.

29. (Previously Presented) An exposure apparatus comprising:

an optical system, which directs an exposure beam emitted from a light source onto a substrate, said optical system including a casing and an optical element, said casing having a closed space and said optical element being disposed in the closed space;

a first supplier, which supplies an inert gas into the closed space;

a second supplier, which supplies a gas, containing oxygen, into the closed space;

a discharger, which discharges the gas from the closed space; and

a controller for changing a wavelength of the exposure beam between an exposure process for the substrate and a cleaning process for the optical element, wherein said controller oscillates the wavelength region continuously.

30. (Previously Presented) An exposure apparatus comprising:

an optical system, which directs an exposure beam emitted from a light source onto a substrate, said optical system including a casing and an optical element, said casing having a closed space and said optical element being disposed in the closed space;

a first supplier, which supplies an inert gas into the closed space;

a second supplier, which supplies a gas, containing oxygen, into the closed space;

a discharger, which discharges the gas from the closed space; and

a controller for changing a wavelength of the exposure beam between an exposure process for the substrate and a cleaning process for the optical element,

wherein said controller controls actuation of said light source.

31. (Previously Presented) An exposure apparatus comprising:

an optical system, which directs an exposure beam emitted from a light source onto a substrate, said optical system including a casing and an optical element, said casing having a closed space and said optical element being disposed in the closed space;

a first supplier, which supplies an inert gas into the closed space;

a second supplier, which supplies a gas, containing oxygen, into the closed space;

a discharger, which discharges the gas from the closed space; and

a controller for changing a wavelength of the exposure beam between an exposure process for the substrate and a cleaning process for the optical element,

wherein said controller inserts a wavelength changing element into a path of the exposure beam.

32. (Previously Presented) An apparatus according to Claim 31, wherein said wavelength changing element is a harmonic wave producing element.

33-36. (Cancelled)

37. (Previously Presented) A device manufacturing method comprising the steps of:  
providing an exposure apparatus comprising:

(i) an optical system, which directs an exposure beam emitted from a light source onto a substrate, said optical system including a casing and an optical element, said casing having a closed space and said optical element being disposed in the closed space,

(ii) a first supplier, which supplies an inert gas into the closed space,

(iii) a second supplier, which supplies a gas, containing oxygen, into the closed space,

(iv) a discharger, which discharges the gas from the closed space, and

(v) a controller for changing a wavelength of the exposure beam between an exposure process for the substrate and a cleaning process for the optical element;

exposing a substrate by use of the exposure apparatus; and

developing the exposed substrate.

38-40. (Cancelled)

41. (Previously Presented) A device manufacturing method, comprising the steps of:  
providing an exposure apparatus comprising:

(i) an optical system, which directs an exposure beam emitted from a light source onto a substrate, said optical system including a casing and an optical element, said casing having a closed space and said optical element being disposed in the closed space,

(ii) a first supplier, which supplies an inert gas into the closed space,

(iii) a second supplier, which supplies a gas, containing oxygen, into the closed space, and

(iv) a controller, which controls concentration of oxygen in the closed space;

exposing a substrate by use of the exposure apparatus; and

developing the exposed substrate.

42-47. (Cancelled)

48. (Previously Presented) An exposure apparatus comprising:

an optical system, which directs an exposure beam emitted from a light source onto a substrate, said optical system including a casing and an optical element, said casing having a closed space and said optical element being disposed in the closed space;

a first supplier, which supplies an inert gas into the closed space;

a second supplier, which supplies a gas, containing oxygen, into the closed space; and

a controller, which controls the first supplier and the second supplier,

wherein said controller functions so that, before exposure of the substrate, the inside of the closed space is filled with substantially only the inert gas.

49. (Previously Presented) A device manufacturing method, comprising the steps of:  
providing an exposure apparatus comprising:

(i) an optical system, which directs an exposure beam emitted from a light source onto a substrate, said optical system including a casing and an optical element, said casing having a closed space and said optical element being disposed in the closed space,

(ii) a first supplier, which supplies an inert gas into the closed space,

(iii) a second supplier, which supplies a gas, containing oxygen, into the closed space, and

(iv) a controller, which controls the first supplier and the second supplier;

exposing a substrate by use of the exposure apparatus; and

developing the exposed substrate.

50. (Cancelled)

51. (Cancelled)



52. (Previously Presented) An exposure apparatus comprising:

an optical system, which directs an exposure beam emitted from a light source onto a substrate, said optical system including a casing and an optical element, said casing having a closed space and said optical element being accommodated in said closed space;

a first supplier, which supplies an inert gas into said closed space and said casing; and

a second supplier, which supplies air into said closed space.

53. (Previously Presented) A device manufacturing method, comprising the steps of:

providing an exposure apparatus as recited in Claim 52;

exposing a substrate by use of the exposure apparatus; and

developing the exposed substrate.

54-57. (Cancelled)